Résiste® 165 PF



Label Facestock



Key Features

- · Made with our industry-leading next generation thermal chemistry (free of phenolic developers)
 - · Unmatched resistance to fading
 - Aquatic-friendly
- · Lower energy required to print high-contrast images
- · Improved resistance to heat, water, and alcohol
- · Imaging speed up to 8 ips

Applications

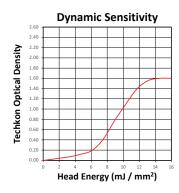
- · Package Delivery Labels
- · Logistics Labels

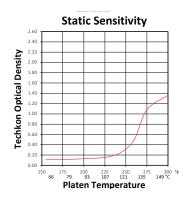


Résiste® 165 PF is a top-coated direct thermal label facestock that was specifically designed with our patent-pending phenol-free direct thermal chemistry to revolutionize package delivery and logistics direct thermal label production with enhanced end-user performance and value.

Product Characteristics – Provisional Data

Cali	per	3.0 +/- 0.2 mils 76.2 +/- 5 μm
Basi	s Weight 17 x 22–500 (lbs) g/m2	19.0 +/- 1.4 71.6 +/- 3.4
The	rmal Response - Nominal Static (°C ± 5°)	
	Initial Activation Temperature 0.2 ODU 1.0 ODU	113° C, 236° F 133° C, 272° F
	Maximum Density (ODU) Temperature Required	1.36 148° C
	Dynamic—Atlantek 400 (mJ/mm2) Initial Printer Energy 0.2 ODU 1.0 ODU	6.1 9.7
	Maximum Density (ODU) Energy Required	1.6 16.0
Brightness (UV Excluded)		86.92
Gurley Stiffness Nominal (mg)		MD 90 CD 35
Elmendorf Tear Nominal (g)		MD 45 CD 45
Tensile (lbs/in)		MD 37 CD 17
Park	er Print Surface	1.15







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A phenol-free value label for package delivery & logistics applications

